



TYPE

**PRODUCT APPLICATION
SPECIFICATION**

SPEC. NO

Revision.

X1

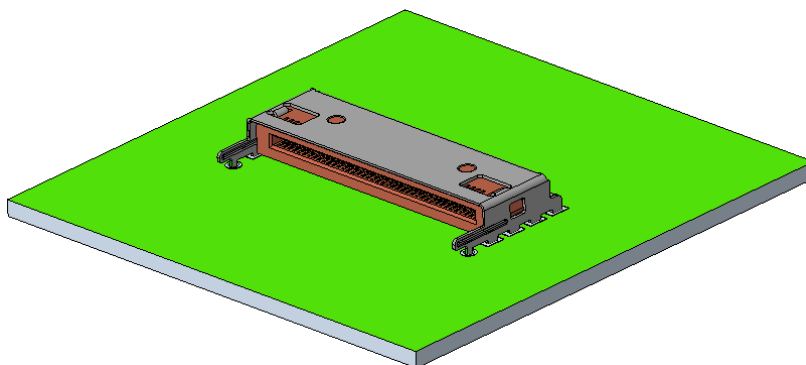
Date

2026/07/20

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ULP SERIES Connector

**Prepared by:**

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Approved by:

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Date:

2026.07.20

Date:

2026.07.20

Date:

2026.07.20

1 OBJECTIVE

This specification provides information and requirements regarding customer application of the ULP SERIES. This specification is intended to provide general guidance for application process development. It is recognized that no single application process will work under all customer scenarios and that customers will develop their own application processes to meet their needs. However, if the application process differ greatly from the one recommended, Luxshare cannot guarantee results.

2 SCOPE

This specification provides information and requirements regarding customer installation and reworking process of the ULP SERIES Connector.

3 DRAWINGS AND APPLICABLE DOCUMENTS

- Luxshare Product Specification:
- Application Luxshare Customer Drawings;
- Luxshare Application Specification:

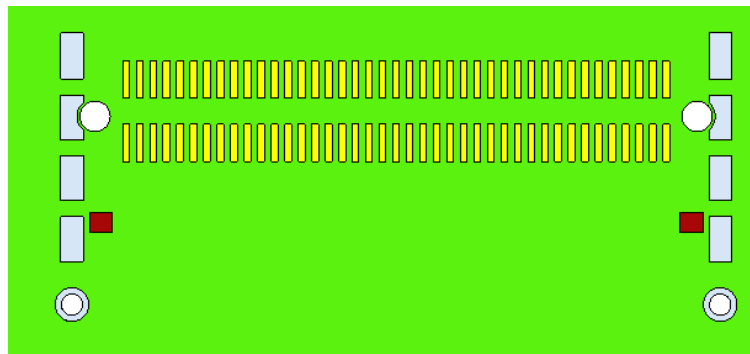
In the event of a conflict between this application specification and the drawing, the drawing will take precedence. Customers are advised to refer to the latest revision of Luxshare product drawings for appropriate details.

4 INSTALLATION PROCESS

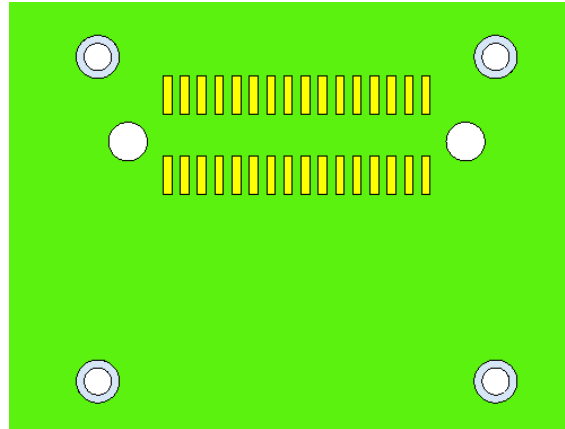
This document is meant to be an application guide. If there is a conflict between the product drawings and specifications, the drawings take precedence.

4.1 CONNECTOR SMT PROCESS

- 4.1.1 Brush solder paste: Apply an even layer of solder paste to the solder pad (terminals, PAD, etc.) of the connector to be soldered.



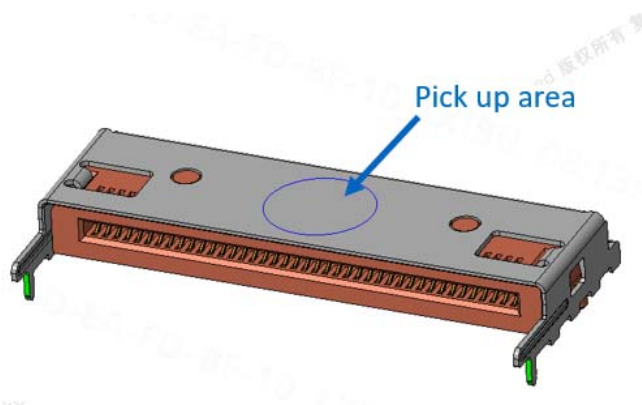
(ULP 82P)



(ULP 32P)

- a. Recommended soldering sequence: If soldering upside down, the first side must be protected from falling. (it is recommended that a fixture is used) Meanwhile, it is recommended that to use glue to fix the first side connector.
- b. Recommended the stencil thickness is 0.15mm.

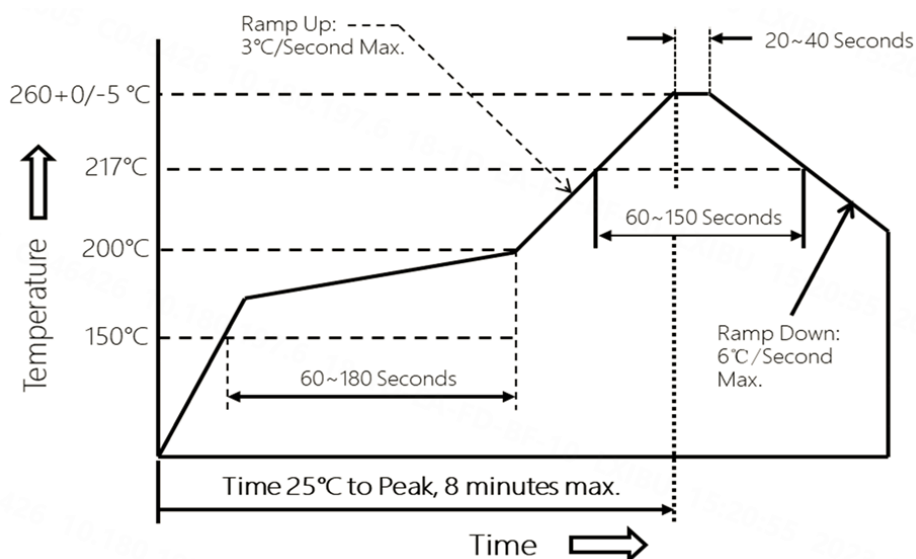
4.1.2 Pick and place: When the connector is absorbed into the pad, the suction nozzle shall be placed in the pick up area on the top of the connector.



4.1.3 IR Reflow



a. Recommended reflow profile below.

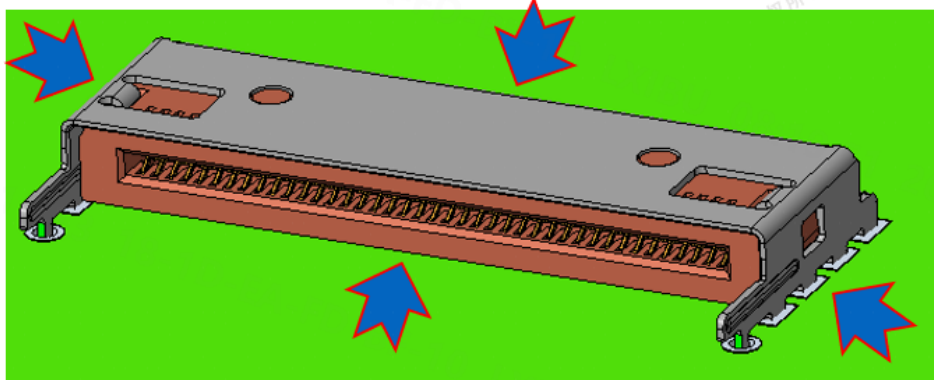


b. Recommended to use reflow welding furnace above 8 temperature zone (nitrogen protection measures are recommended)

5 Rework Process

5.1 Connector unsoldering

- Heat connector solder to molten state, then remove the connector lightly.
- To minimize damage to PCB and components, if allows, heat the connector from underneath.





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REVISION RECORD

Rev	Page	Description	EC#	Date
X1	All	Release specification		2026/07/20